TOSHIBA 2SK3075

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE

2 S K 3 0 7 5

RF POWER MOSFET

FOR VHF- AND UHF-BAND POWER AMPLIFIER

Output Power : $P_{O} \ge 7.5W$ Power Gain : $G_P \ge 11.7dB$ Drain Efficiency $\cdot \eta_{\mathbf{D}} \ge 50\%$

MAXIMUM RATINGS (Ta = 25°C)

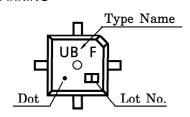
CHARACTERISTIC	SYMBOL	RATING	UNIT
Drain-Source Voltage	$v_{ m DSS}$	30	V
Gate-Source Voltage	v_{GSS}	25	V
Drain Current	$I_{\mathbf{D}}$	5	Α
Drain Power Dissipation	P_{D}^{*}	20	W
Channel Temperature	$\mathrm{T_{ch}}$	150	°C
Storage Temperature Range	$\mathrm{T_{stg}}$	-45~150	°C

*: Tc=25°C When mounted on a 1.6mm glass epoxy PCB

GATE SOURCE (HEAT SINK) 3. DRAIN **JEDEC EIAJ TOSHIBA** 2-5N1A

Unit in mm

MARKING



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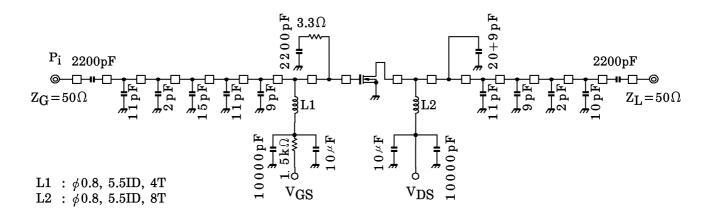
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

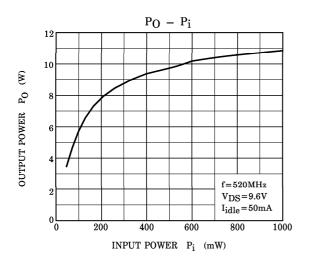
CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Output Power	PO	$\begin{aligned} &V_{DS}\!=\!9.6V\\ &\text{Iidle}\!=\!50\text{mA}\left(V_{GS}\!=\!\text{adjust}\right)\\ &f\!=\!520\text{MHz},P_{i}\!=\!500\text{mW}\\ &Z_{G}\!=\!Z_{L}\!=\!50\Omega \end{aligned}$	7.5	_	_	w
Drain Efficiency	$\eta_{\mathbf{D}}$		50	_	_	%
Power Gain	$G_{\mathbf{P}}$		11.7	_	_	dB
Gate Threshold Voltage	$V_{ m th}$	$V_{DS} = 9.6V, I_{D} = 0.5 \text{mA}$	1.0	1.5	2.0	V
Drain Cut-off Current	$I_{ m DSS}$	$V_{DS}=20V, V_{GS}=0$	_	_	10	μ A
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=10V, V_{DS}=0$		ı	5	μ A

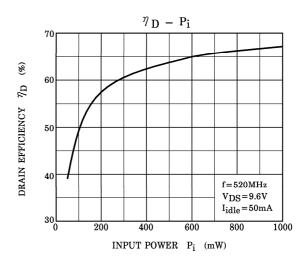
HANDLING PRECAUTION

• When handling individual devices, be sure that working desks, human bodies and soldering iron are protected against electrostatic electricity.

RF OUTPUT POWER TEST FIXTURE







CAUTION

These are only typical curves and devices are not necessarily guaranteed at these curves.